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Sommario/riassunto

The growing demand for instant and reliable communication means that photonic circuits are increasingly finding applications in optical communications systems. One of the prime candidates to provide satisfactory performance at low cost in the photonic circuit is silicon. Whilst silicon photonics is less well developed as compared to some other material technologies, it is poised to make a serious impact on the telecommunications industry, as well as in many other applications, as other technologies fail to meet the yield/performance/cost trade-offs. Following a sympathetic tutorial approach,